

Product Change Notification - JAON-16TUGT945

Date: 21 Jun 2016
Product Category: Memory
Notification subject: CCB 2652 Initial Notice: Qualification of G600V molding compound for products available in 8L SOIC Chip On Lead (COL) package assembled at MTAI assembly site.
Notification text: **PCN Status:**
Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of G600V molding compound for products available in 8L SOIC Chip On Lead (COL) package assembled at MTAI assembly site.

Pre Change:

Using SG-8300GM molding compound

Post Change:

Using G600V molding compound

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	MTAI assembly site	MTAI assembly site
Wire material	Au wire	Au wire
Die attach material	8006NS	8006NS
Molding compound material	SG-8300GM	G600V
Lead frame material	CDA194	CDA194

Impacts to Data Sheet:

None

Reason for Change:

To improve manufacturability by qualifying G600V molding compound.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

August 2016

Note: Please be advised the qualification completion times may be extended because of unforeseen business

conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date.

Time Table Summary:

Workweek	June 2016					-->	August 2016			
	22	23	24	25	26		31	32	33	34
Initial PCN Issue Date				X						
Qual Report Availability							X			
Final PCN Issue Date							X			

Markings to Distinguish Revised from Unrevised Devices:

Traceability code

Revision History:

June 21, 2016: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_JAON-16TUGT945_Qual_Plan.pdf](#)

[PCN_JAON-16TUGT945_Affected_CPN.pdf](#)

[PCN_JAON-16TUGT945_Affected_CPN.xls](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_JAON-16TUGT945
CATALOG_PART_NBR
23A1024-E/SN
23A1024-I/SN
23A1024T-E/SN
23A1024T-I/SN
23A512-E/SN
23A512-I/SN
23A512T-E/SN
23A512T-I/SN
23LC1024-E/SN
23LC1024-I/SN
23LC1024T-E/SN
23LC1024T-I/SN
23LC512-E/SN
23LC512-I/SN
23LC512T-E/SN
23LC512T-I/SN
23LCV1024-I/SN
23LCV1024T-I/SN
23LCV512-I/SN
23LCV512T-I/SN
24AA128-I/SN
24AA128T-I/SN
24AA512-I/SN
24AA512T-I/SN
24FC128-I/SN
24FC128T-I/SN
24FC512-I/SN
24FC512T-I/SN
24LC128-I/SN
24LC128T-I/SN
24LC256-I/SN
24LC256T-I/SN
24LC512-E/SN
24LC512-I/SN
24LC512T-E/SN
24LC512T-I/SN
25AA128-I/SN
25AA128T-I/SN
25AA256-I/SN
25AA256T-I/SN
25LC128-E/SN
25LC128-I/SN
25LC128T-E/SN

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Affected Catalog Part Numbers (CPN)

PCN_JAON-16TUGT945
CATALOG_PART_NBR
25LC128T-I/SN
25LC256-I/SN
25LC256T-I/SN



MICROCHIP

QUALIFICATION PLAN

PCN #: JAON-16TUGT945

Date
June 1, 2016

**Qualification of G600V molding compound for
products available in 8L SOIC Chip-On-Lead (COL)
package assembled at MTAI assembly site.**

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Purpose: Qualification of G600V molding compound for products available in 8L SOIC chip-on-lead (COL) package assembled at MTAI assembly site.

CCB No.: 2652

Misc.	Assembly site	MTAI
	BD Number	BDM-001096 rev.B
	MP Code (MPC)	TVAA14CYXD00
	Part Number (CPN)	23LC512-E/SN
Lead-Frame	Paddle size	116x178 mils
	Material	CDA194
	Surface	Bare Cu DAP
	Process	Etched
	Lead-lock	No
	Part Number	10100811
	Lead Plating	Matte Tin
Bond Wire	Material	Au
Die Attach	Part Number	8006NS
	Conductive	No
MC	Part Number	G600V
PKG	PKG Type	SOIC
	Pin/Ball Count	8
	PKG width/size	150 mils
Die	Die Thickness	8 mils
	Die Size	75.1 x 112.8 mils

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	3	24	0 fails after TC	5	30 bonds from a minimum of 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	3	24	0	5	30 bonds from a minimum of 5 devices.
Wire Sweep		5	0	3	15	0		Required for any reduction in wire bond thickness.
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	
HTSL (High Temp Storage Life)	+175 C for 504 hours or 150°C for 1008 hrs. Electrical test pre and post stress at +25°C and hot temp. (1 lot to be tested at 125C)	45	5	1	50	0	10	Must be in progress at time of package release to production, but completion is not required for release to production.
Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020D for package type; Electrical test pre and post stress at +25°C. MSL1 @ 260°C (1 lot to be tested at 125C)	231	15	3	738	0	15	Spares should be properly identified. 77 parts from each lot to be used for HAST, Autoclave, Temp Cycle test.
HAST	+130°C/85% RH for 96 hours or 110°C/85%RH for 264 hours. Electrical test pre and post stress at +25°C and hot temp. (1 lot to be tested at 125C)	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Unbiased HAST	+130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs. Electrical test pre and post stress at +25°C. (1 lot to be tested at 125C)	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	-65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp 85C; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress. (1 lot to be tested at 125C)	77	5	3	246	0	15	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.